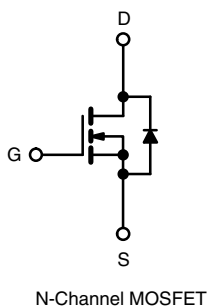
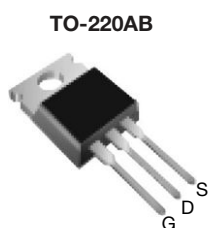


## Power MOSFET

### PRODUCT SUMMARY

$V_{DS}$ (V)	400	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10$ V	1.0
$Q_g$ (Max.) (nC)	22	
$Q_{gs}$ (nC)	5.8	
$Q_{gd}$ (nC)	9.3	
Configuration	Single	



### FEATURES

- Low Gate Charge  $Q_g$  results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic  $dV/dt$  Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective  $C_{oss}$  Specified
- Compliant to RoHS Directive 2002/95/EC


**RoHS\***  
COMPLIANT

### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching

### TYPICAL SMPS TOPOLOGIES

- Single Transistor Flyback Xfmr. Reset
- Single Transistor Forward Xfmr. Reset (Both US Line Input Only)

### ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	IRF730APbF
	SiHF730A-E3
SnPb	IRF730A
	SiHF730A

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	400	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	
Continuous Drain Current	$I_D$	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	22	
Linear Derating Factor		0.6	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	290	mJ
Repetitive Avalanche Current <sup>a</sup>	$I_{AR}$	5.5	A
Repetitive Avalanche Energy <sup>a</sup>	$E_{AR}$	7.4	mJ
Maximum Power Dissipation	$P_D$	74	W
Peak Diode Recovery $dV/dt$ <sup>c</sup>	$dV/dt$	4.6	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s	300 <sup>d</sup>	
Mounting Torque	6-32 or M3 screw	10	lbf · in
		1.1	N · m

#### Notes


- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting  $T_J = 25^\circ\text{C}$ ,  $L = 19$  mH,  $R_g = 25\ \Omega$ ,  $I_{AS} = 5.5$  A (see fig. 12).
- $I_{SD} \leq 5.5$  A,  $dI/dt \leq 90$  A/ $\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150^\circ\text{C}$ .
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.70	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.50	-	
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	

**SPECIFICATIONS** ( $T_J = 25\text{ °C}$ , unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		400	-	-	V
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.5	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.0	-	4.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 30 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V		-	-	25	μA
		V <sub>DS</sub> = 320 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C		-	-	250	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.3 A <sup>b</sup>	-	-	1.0	Ω
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 3.3 A		3.1	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1.0 MHz, see fig. 5		-	600	-	pF
Output Capacitance	C <sub>OSS</sub>			-	103	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	4.0	-	
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 1.0 V, f = 1.0 MHz	-	890	-	
Effective Output Capacitance	C <sub>OSS eff.</sub>		V <sub>DS</sub> = 320 V, f = 1.0 MHz	-	30	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.5 A, V <sub>DS</sub> = 320 V see fig. 6 and 13 <sup>b</sup>	-	-	22	nC
Gate-Source Charge	Q <sub>gs</sub>			-	-	5.8	
Gate-Drain Charge	Q <sub>gd</sub>			-	-	9.3	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 200 V, I <sub>D</sub> = 3.5 A R <sub>g</sub> = 12 Ω, R <sub>D</sub> = 57 Ω, see fig. 10 <sup>b</sup>		-	10	-	ns
Rise Time	t <sub>r</sub>			-	22	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	20	-	
Fall Time	t <sub>f</sub>			-	16	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	5.5	A
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	22	
Body Diode Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 5.5 A, V <sub>GS</sub> = 0 V <sup>b</sup>		-	-	1.6	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 3.5 A, dI/dt = 100 A/μs <sup>b</sup>		-	370	550	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	1.6	2.4	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and L <sub>D</sub> )					

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).  
b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .  
c.  $C_{oss\text{ eff.}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .

## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

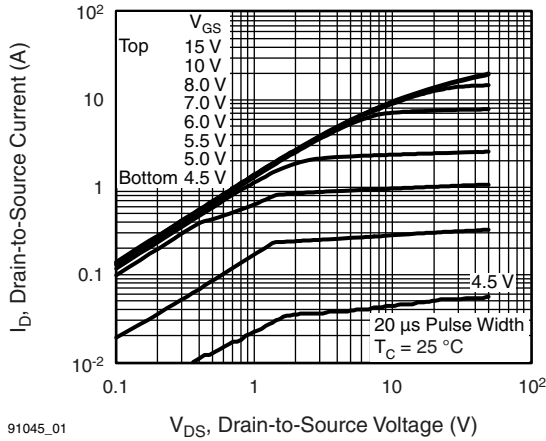


Fig. 1 - Typical Output Characteristics

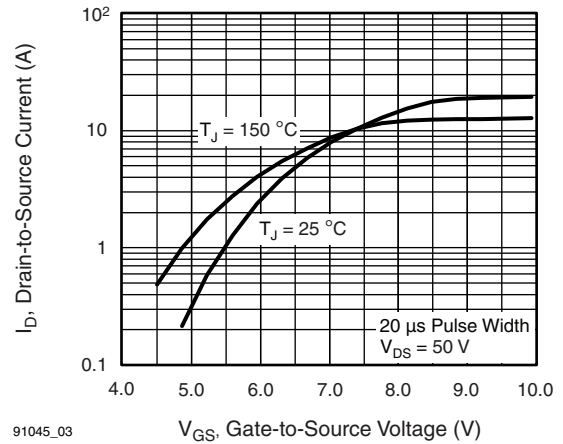


Fig. 3 - Typical Transfer Characteristics

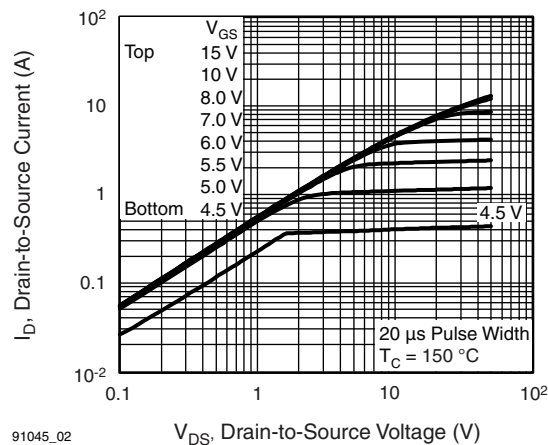


Fig. 2 - Typical Output Characteristics

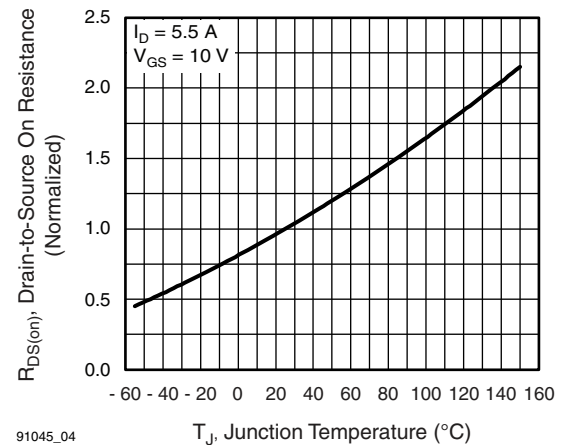
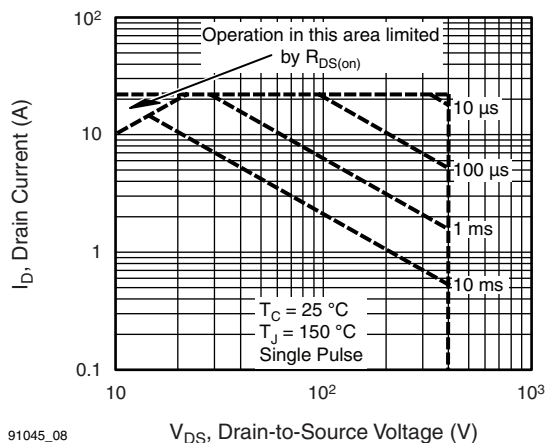
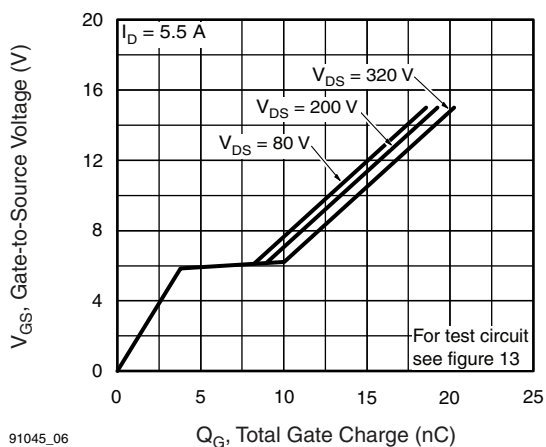
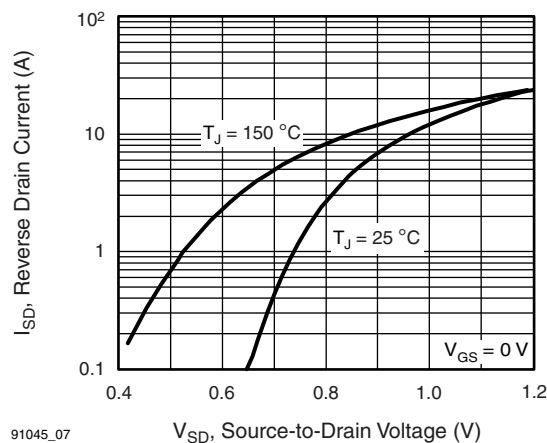
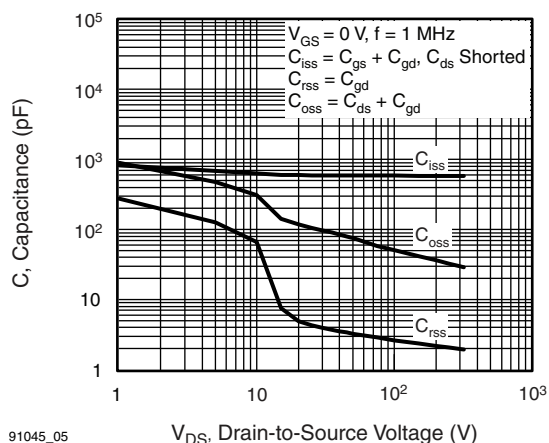
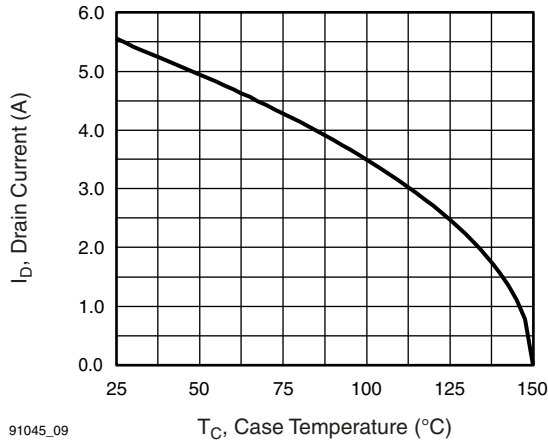
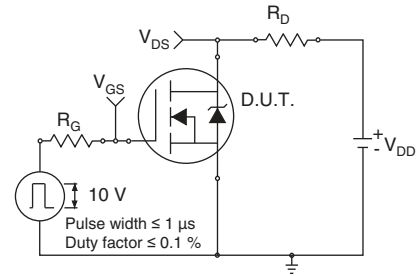


Fig. 4 - Normalized On-Resistance vs. Temperature

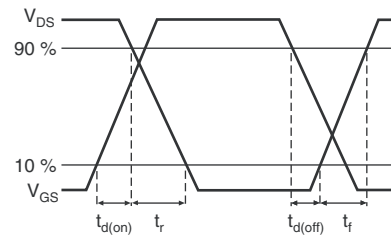




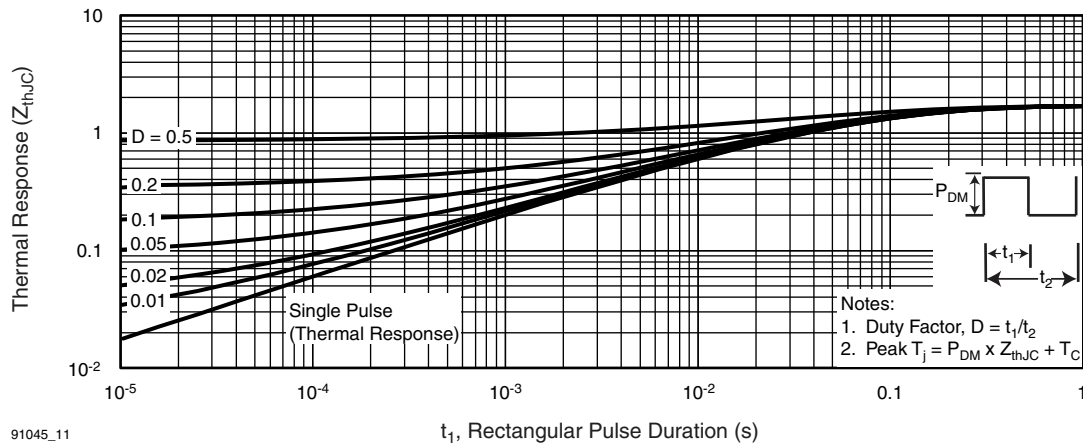
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



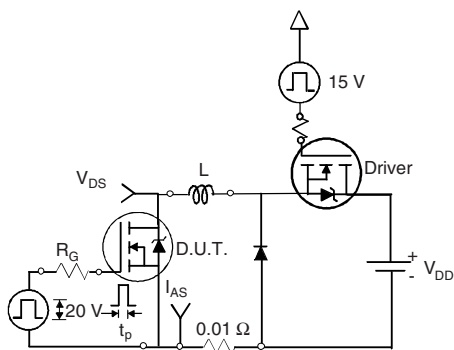
**Fig. 10a - Switching Time Test Circuit**



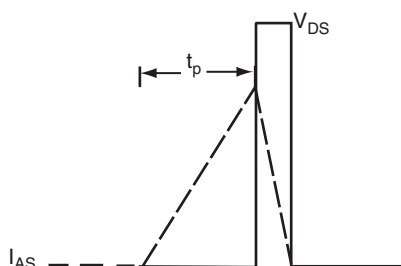
**Fig. 10b - Switching Time Waveforms**



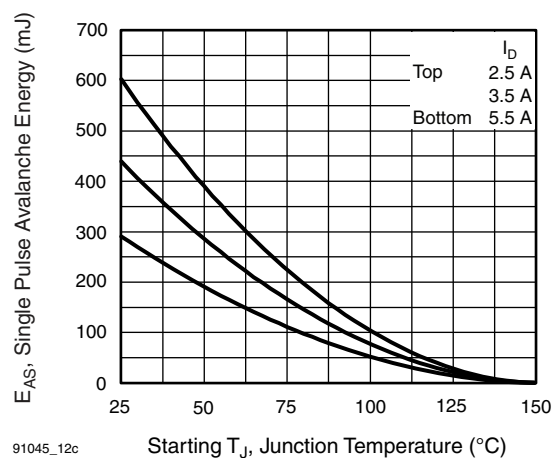
**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



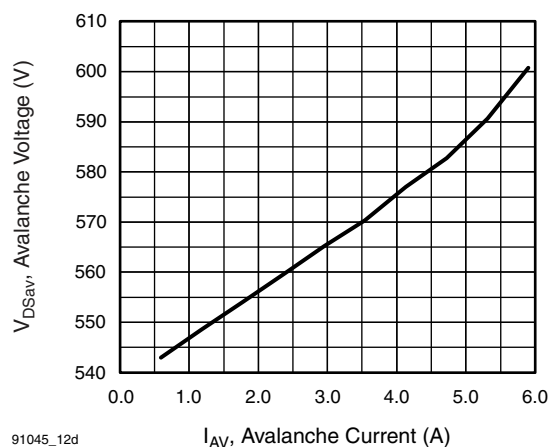
**Fig. 12a - Unclamped Inductive Test Circuit**



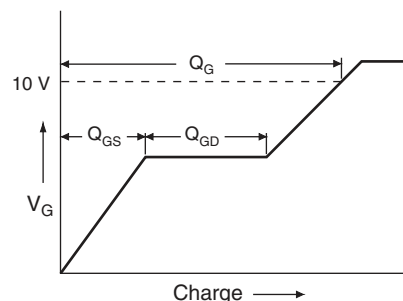
**Fig. 12b - Unclamped Inductive Waveforms**



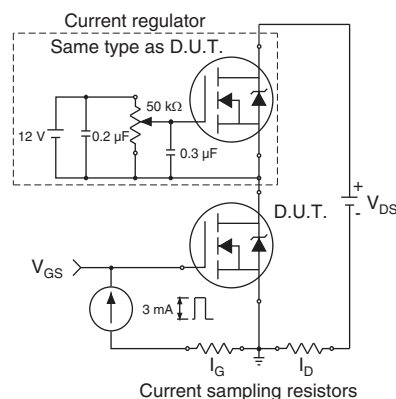
**Fig. 12c - Maximum Avalanche Energy vs. Drain Current**



**Fig. 12d - Typical Drain Source Voltage vs. Avalanche Current**

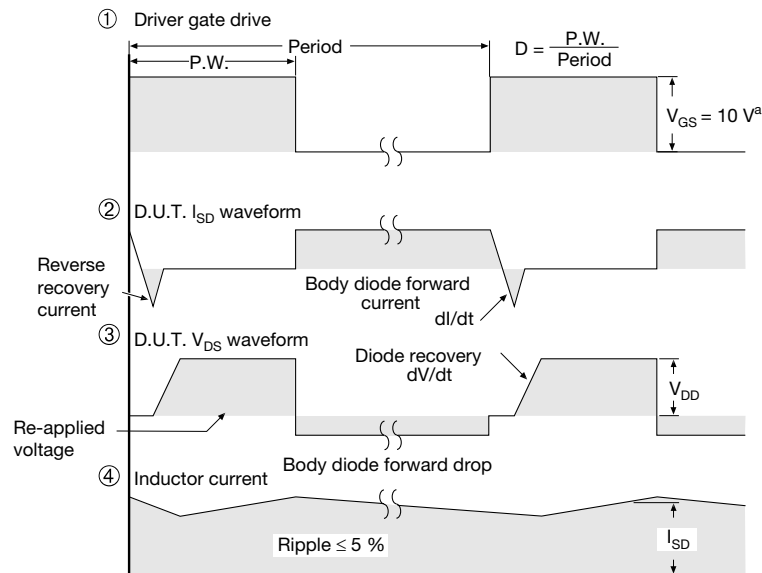
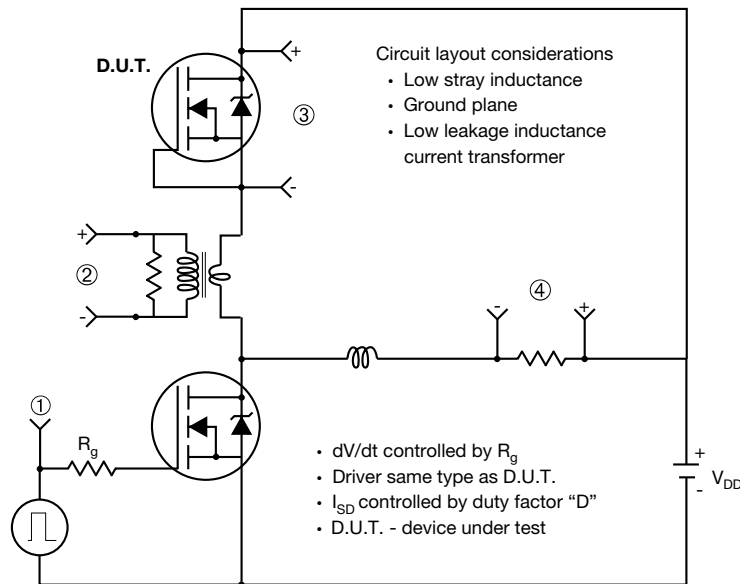


**Fig. 13a - Basic Gate Charge Waveform**



**Fig. 13b - Gate Charge Test Circuit**

## Peak Diode Recovery dV/dt Test Circuit



### Note

a.  $V_{GS} = 5\text{ V}$  for logic level devices

**Fig. 14 - For N-Channel**

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## TO-220-1



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
$\varnothing P$	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

ECN: X15-0364-Rev. C, 14-Dec-15  
DWG: 6031

### Note

- M\* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

## Package Picture







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